

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Kaushik Chanda</td><td>05/19/2008</td></tr><tr><td>Ronald G. Filippi</td><td>05/05/2008</td></tr><tr><td>Charles C. Goldsmith</td><td>05/05/2008</td></tr><tr><td>Ping-Chuan Wang</td><td>05/02/2008</td></tr><tr><td>Chih-Chao Yang</td><td>05/05/2008</td></tr></tbody></table>	Name	Execution Date	Kaushik Chanda	05/19/2008	Ronald G. Filippi	05/05/2008	Charles C. Goldsmith	05/05/2008	Ping-Chuan Wang	05/02/2008	Chih-Chao Yang	05/05/2008	
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Chih-Chao Yang	05/05/2008												
RECEIVING PARTY DATA													
Name:	International Business Machines Corporation												
Street Address:	New Orchard Road												
City:	Armonk												
State/Country:	NEW YORK												
Postal Code:	10504												
PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12127878</td></tr></tbody></table>	Property Type	Number	Application Number:	12127878									
Property Type	Number												
Application Number:	12127878												
CORRESPONDENCE DATA													
Fax Number:	(845)892-6363												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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Email:	lindadoh@us.ibm.com												
Correspondent Name:	International Business Machines Corp.												
Address Line 1:	2070 Rt. 52												
Address Line 2:	M/D 482												
Address Line 4:	Hopewell Junction, NEW YORK 12533												
ATTORNEY DOCKET NUMBER:	FIS920080043US1												
NAME OF SUBMITTER:	Lisa U. Jaklitsch												

CH \$40.00 12127878

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PATENT  
REEL: 021025 FRAME: 0282

**Total Attachments: 4**

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**PATENT**

**REEL: 021025 FRAME: 0283**

**ASSIGNMENT**

Whereas, we

**INVENTOR  
AND CITY**

- (1) **Kaushik Chanda** of Fishkill, County of Dutchess and State of New York;  
 (2) **Ronald G. Filippi** of Wappingers Falls, County of Dutchess and State of New York;  
 (3) **Charles C. Goldsmith** of Poughkeepsie, County of Dutchess and State of New York;  
 (4) **Ping-Chuan Wang** of Hopewell Junction, County of Dutchess and State of New York;  
 (5) **Chih-Chao Yang** of Glenmont, County of Albany and State of New York;

have invented certain improvements in

**TITLE****STRESS LOCKING LAYER FOR RELIABLE METALLIZATION****DATES THAT  
INVENTORS  
SIGNED THE  
DECLARATION**

and executed, respectively, a United States patent application therefor on

- (1) 5/19, 2008, (2) 5/5, 2008, (3) 5/5, 2008,  
 (4) 5/2, 2008, (5) \_\_\_\_\_, 2008.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

**Signed and sealed**

- (1) Kaushik on 5/19, 2008  
 Kaushik Chanda
- (2) Ronald G. Filippi on 5/5, 2008  
 Ronald G. Filippi
- (3) Charles C. Goldsmith on 5/5, 2008  
 Charles C. Goldsmith
- (4) Ping-Chuan Wang on 5/2, 2008  
 Ping-Chuan Wang

**PATENT****REEL: 021025 FRAME: 0284**

(5) \_\_\_\_\_  
Chih-Chao Yang

on \_\_\_\_\_, 2008

**ASSIGNMENT**

Whereas, we

**INVENTOR  
AND CITY**

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- (2) **Ronald G. Filippi** of Wappingers Falls, County of Dutchess and State of New York;
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- (1) \_\_\_\_\_, 2008, (2) \_\_\_\_\_, 2008, (3) \_\_\_\_\_, 2008,
- (4) \_\_\_\_\_, 2008, (5) May 5, 2008.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

**Signed and sealed**

- (1) \_\_\_\_\_ on \_\_\_\_\_, 2008  
Kaushik Chanda
- (2) \_\_\_\_\_ on \_\_\_\_\_, 2008  
Ronald G. Filippi
- (3) \_\_\_\_\_ on \_\_\_\_\_, 2008  
Charles C. Goldsmith
- (4) \_\_\_\_\_ on \_\_\_\_\_, 2008  
Ping-Chuan Wang

(5) Chih-Chao Yang

on May 5, 2008